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REVISIONS		
REV #	DESCRIPTION	DATE
REV #	CCN #	DDMMYY

**FABRICATION NOTES:**

- FABRICATE PCB IN ACCORDANCE WITH IPC-6012C, CLASS 2; PER IPC-6011.  
PCB SHALL BE MANUFACTURED USING 1-SPEED OR EQUIVALENT.
- MATERIALS:
  - LAMINATE AND PREPREG (B-STAGE) TO BE IN ACCORDANCE WITH IPC-4101/126. (MIN.TG 180)
  - COPPER FOIL TO BE IN ACCORDANCE WITH IPC-MP-150. UNLESS OTHERWISE SPECIFIED, ALL COPPER WEIGHT FOR INNER SIGNAL LAYERS AND INNER PLANE LAYERS TO BE 35UM (1 OZ.). FOR OUTER LAYERS 1.31 OZ. COPPER WEIGHT IS TO BE CONSIDERED "FINISHED".  
THE COPPER FOIL THICKNESS TOLERANCES SHALL BE AS PER IPC 6012C TABLE NO.1-7 AND 3-8.
- ALL HOLES SHALL BE LOCATED WITHIN 0.15MM DIAMETER OF TRUE POSITION.  
LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.125MM.
- BOW AND TWIST SHALL NOT EXCEED MORE THAN 0.75% OF THE DESIGN LENGTH.
- CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20% FROM ITS ORIGINAL DATA. INCREASE FOR MATCHING IMPEDANCE MISTRAL SHALL APPROVE THE MODIFIED WIDTHS AND SPACING.  
TRACE WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.
- AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.
- FINISH:
  - ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIG, ELECTROLESS NICKEL/IMMERSION GOLD, ELECTROLESS NICKEL SHALL BE 3-4 MICRONS, TYPICAL IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
  - APPLY LIQUID PHOTO IMAGEABLE SOLDER MASK PER IPC-BM-840, CLASS H, TO BOTH SIDES OF THE BOARD OVER BARE COPPER.  
VIA HOLES THAT HAVE MASK OPEN SHALL BE FILLED WITH NON CONDUCTIVE INK AND CAP PLATED, ALL OTHER VIA HOLES SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK, ONLY SOLDERMASK IMAGES THAT ARE 0.08(0.003") PER SIDE SHALL BE REDUCED IF REQUIRED.  
ALL OTHER SOLDER MASK IMAGES SHALL NOT BE ENLARGED. DEFAULT COLOR OF SOLDER MASK SHALL BE GREEN.
- SILKSCREEN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PAD. CLIPPING OF SILK SCREEN SHALL BE ALLOWED IF THE SILK SCREEN FALLS ON SOLDERABLE AREAS.
- SURFACE AND VIA HOLES FINISH SHALL NOT BE LESS THAN 20UM (0.00079"), INCREASE OF LASER VIA'S, BLIND VIA'S SHALL NOT BE LESS THAN 12UM (0.00047") AND BURIED VIA'S SHALL NOT BE LESS THAN 15UM (0.0006").
- ALL HOLES SURROUNDED BY LAND <0.010" SHALL BE COMPLAINT TO IPC6012, CLASS 2.
- MARKING:
  - BOARD SHALL MEET THE REQUIREMENTS OF UL-7968 WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, UL FILE NUMBER, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE RENDERED IN SILKSCREEN.
- TEST REQUIREMENTS:
  - 100% NET LIST ELECTRICAL VERIFICATION USING MISTRAL SUPPLIED IPC-D-356 NET LIST FOR OPENS AND SHORTS.
- THROWING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.
- TEAR DROPS SHALL BE ADDED ON INTERNAL AND EXTERNAL LAYER FOR ALL THE VIA'S AND THROUGH HOLE PADS.
- FINISHED PCB THICKNESS SHALL BE 0.085" +/-10%.
- MIN TRACE WIDTH/SPACING ON BOARD IS 0.003"/0.0032".
- ALL THE IMPEDANCE SHALL BE MATCHED AS PER IMPEDANCE TABLE WITH +/-10% TOLERANCE.
- ENSURE THAT UL REGISTERED E-FILE NUMBER SHALL BE PRINTED ON PCB SILKSCREEN
- ALL UNCONNECTED VIA'S SHALL BE SUPPRESSED IN INTERNAL LAYERS.
- BACKDRILLING TO BE DONE FROM L01 TO L11.
- BACKDRILLING TO BE DONE FROM L16 TO L11.
- BACKDRILLING TO BE DONE FROM L16 TO L04.
- FOR DETAILED STACKUP, PROC118\_STACKUP.PDF SHALL BE REFERRED

BACKDRILL: TOP TO L10-SIGNAL				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
187	7.98	+3.0/-0.0	PLATED	12
START	TARGET	MUST CUT	MUST NOT CUT	
L10	L10	L10	L10	

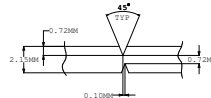
NOTES:  
- DRILL SIZES LISTED IN LEGEND ARE CONSIDERED FINISHED.  
- VENDOR IS REQUIRED TO SELECT TOOLING FOR OVERDRILLING.  
- LEGEND DOES NOT SPECIFY DEPTH INTO ADJACENT DIELECTRIC LAYER.

BACKDRILL: BOTTOM TO L11-ONIN				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
187	7.98	+3.0/-3.0	PLATED	252
START	TARGET	MUST CUT	MUST NOT CUT	
L16	L11	L12	L16	

NOTES:  
- DRILL SIZES LISTED IN LEGEND ARE CONSIDERED FINISHED.  
- VENDOR IS REQUIRED TO SELECT TOOLING FOR OVERDRILLING.  
- LEGEND DOES NOT SPECIFY DEPTH INTO ADJACENT DIELECTRIC LAYER.

BACKDRILL: BOTTOM TO L4-GND2				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
187	7.98	+3.0/-3.0	PLATED	32
START	TARGET	MUST CUT	MUST NOT CUT	
L16	L4	L16	L4	

NOTES:  
- DRILL SIZES LISTED IN LEGEND ARE CONSIDERED FINISHED.  
- VENDOR IS REQUIRED TO SELECT TOOLING FOR OVERDRILLING.  
- LEGEND DOES NOT SPECIFY DEPTH INTO ADJACENT DIELECTRIC LAYER.

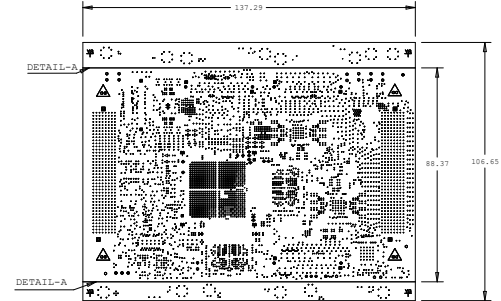


DETAIL-A (V-GROOVE DETAILS)  
SCALE: NTS

DRILL CHART: TOP TO BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
187	7.96	+3.0/-3.0	PLATED	32
187	7.98	+3.0/-0.0	PLATED	12
187	7.99	+3.0/-3.0	PLATED	252
187	8.0	+3.0/-3.0	PLATED	3036
187	10.0	+3.0/-3.0	PLATED	1707
187	36.0	+3.0/-3.0	PLATED	3
187	40.0	+0.0/-0.0	PLATED	19
187	40.0	+2.0/-2.0	PLATED	6
187	40.0	+3.0/-3.0	PLATED	2
187	44.0	+2.0/-2.0	PLATED	3
187	34.0	+1.0/-1.0	NON-PLATED	2
187	40.0	+3.0/-3.0	NON-PLATED	2
187	42.0	+2.0/-2.0	NON-PLATED	6
187	58.0	+3.0/-3.0	NON-PLATED	4
187	66.0	+3.0/-3.0	NON-PLATED	4
187	108.0	+3.0/-3.0	NON-PLATED	4
187	250.0	+3.0/-3.0	NON-PLATED	4

**IMPEDANCE SPECIFICATIONS**

SL#	TYPE	LAYER	TRACEWIDTH (Mils)	SPACING (Mils)	IMPEDANCE (Ohms)	REF LAYER
01	EDGE COUPLED MICROSTRIP	L1/L16	4.7	5.6	100	L2/L15
02	EDGE COUPLED MICROSTRIP	L1/L16	6.3	5.7	90	L2/L15
03	EDGE COUPLED MICROSTRIP	L16	7.4	5.8	85	L15
04	EDGE COUPLED MICROSTRIP	L1	9	5	80	L2
05	EDGE COUPLED MICROSTRIP	L1	4	5.3	120	L3
06	MICROSTRIP	L1	18	-	33	L2
07	MICROSTRIP	L1	13	-	40	L2
08	MICROSTRIP	L1/L16	9	-	50	L2/L15
09	EDGE COUPLED STRIPLINE	L3,L5,L7, L10,L12,L14	3	5	100	L2/L4,L4/L6,L6/L8, L9/L11,L11/L13,L13/L15
10	EDGE COUPLED STRIPLINE	L10,L12,L14	3.8	5	90	L9/L11,L11/L13,L13/L15
11	EDGE COUPLED STRIPLINE	L12,L14	4.3	5	85	L11/L13,L13/L15
12	EDGE COUPLED STRIPLINE	L3,L5	5	5	80	L2/L4,L4/L6
13	EDGE COUPLED STRIPLINE	L7	7.3	5.4	66	L6/L8
14	EDGE COUPLED STRIPLINE	L3	3	15	132	L2/L4
15	STRIPLINE	L3,L5,L7, L10,L12,L14	3.8	-	50	L2/L4,L4/L6,L6/L8, L9/L11,L11/L13,L13/L15
16	STRIPLINE	L7	8	-	33	L6/L8
17	STRIPLINE	L3	3	-	66	L2/L4
18	STRIPLINE	L3,L5,L10	6	-	40	L2/L4,L4/L6,L9/L11



LAYER STACKUP			
LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS (INCHES)
PRIMARY SIDE SILKSCREEN			
PRIMARY SIDE SOLDERMASK			
L01 PRIMARY SIDE	1.31oz		0.00400
L02 GROUND-PLANE-1	1oz.		0.00400
L03 INNER-SIGNAL-1	1oz.		0.00420
L04 GROUND-PLANE-2	1oz.		0.00400
L05 INNER-SIGNAL-2	1oz.		0.00400
L06 GROUND-PLANE-3	1oz.		0.00420
L07 INNER-SIGNAL-3	1oz.		0.00400
L08 POWER-PLANE-1	1oz.		0.00420
L09 POWER-PLANE-2	1oz.		0.00400
L10 INNER-SIGNAL-4	1oz.		0.00420
L11 GROUND-PLANE-4	1oz.		0.00400
L12 INNER-SIGNAL-5	1oz.		0.00420
L13 GROUND-PLANE-5	1oz.		0.00400
L14 INNER-SIGNAL-6	1oz.		0.00420
L15 GROUND-PLANE-6	1oz.		0.00400
L16 SECONDARY SIDE	1.31oz		0.00400
SECONDARY SIDE SOLDERMASK			
SECONDARY SIDE SILKSCREEN			

SIGNATURES		DATE	TEXAS INSTRUMENTS		PROC118E1
LAYOUT BY	UD	160721	TDA4VE, TDA4VL & TDA4AL SOM		Rev S1
REVIEWED BY	ZA	160721			
APPROVED BY	AMB	160721			
					SIZE D
					SCALE: NONE
					SHEET 1 OF 23

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